

Kulicke & Soffa Industries, Inc.

## Kulicke & Soffa to Participate at SMT Hybrid Packaging 2018

SINGAPORE--(BUSINESS WIRE)--Jun. 4, 2018-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SMT Hybrid Packaging 2018 trade show in Nuremberg, Germany, from June 5 through 7, 2018.

Kulicke & Soffa will be showcasing its latest packaging solutions at the SMT Hybrid Packaging trade show Hall 4A, booth #444.

- iFlex T2 – its new design increases feeder capacity by 25% while also excelling at multi-part tray feeding. This multifunctional flexibility makes it a perfect standalone or end-of-line solution for the most demanding, high-mix applications.
- Hybrid Wafer Feeder – an innovative solution that enables the combination of ultra-high-speed passive and active placement with high-accuracy flip-chip bonding directly from wafer is ideal for high-volume System-in-Package (SiP), flip-chip, die-attach, Embedded Component Placement (ECP) and wafer-level-package manufacturing. Placement accuracy up to 7µm @ 3 sigma, provides a compelling alternative to existing commercial solutions.
- Asterion™ – built on an architecture with enhanced capabilities addresses the industry's growing and evolving power control and storage needs. A single platform handles a multitude of interconnect materials such as large aluminum wire, *PowerRibbon*™ and interconnects for battery cells.
- RAPID™ Pro – the first in the latest *GEN-S* high performance wire bonders series, RAPID™ Pro delivers advanced process capabilities, real-time monitoring, diagnostics and traceability to ensure the highest quality and efficient assembly of automotive as well as other high performance semiconductor packages.

Please contact your local sales and services representative for more information on K&S' comprehensive solutions.

### About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. ([www.kns.com](http://www.kns.com))

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